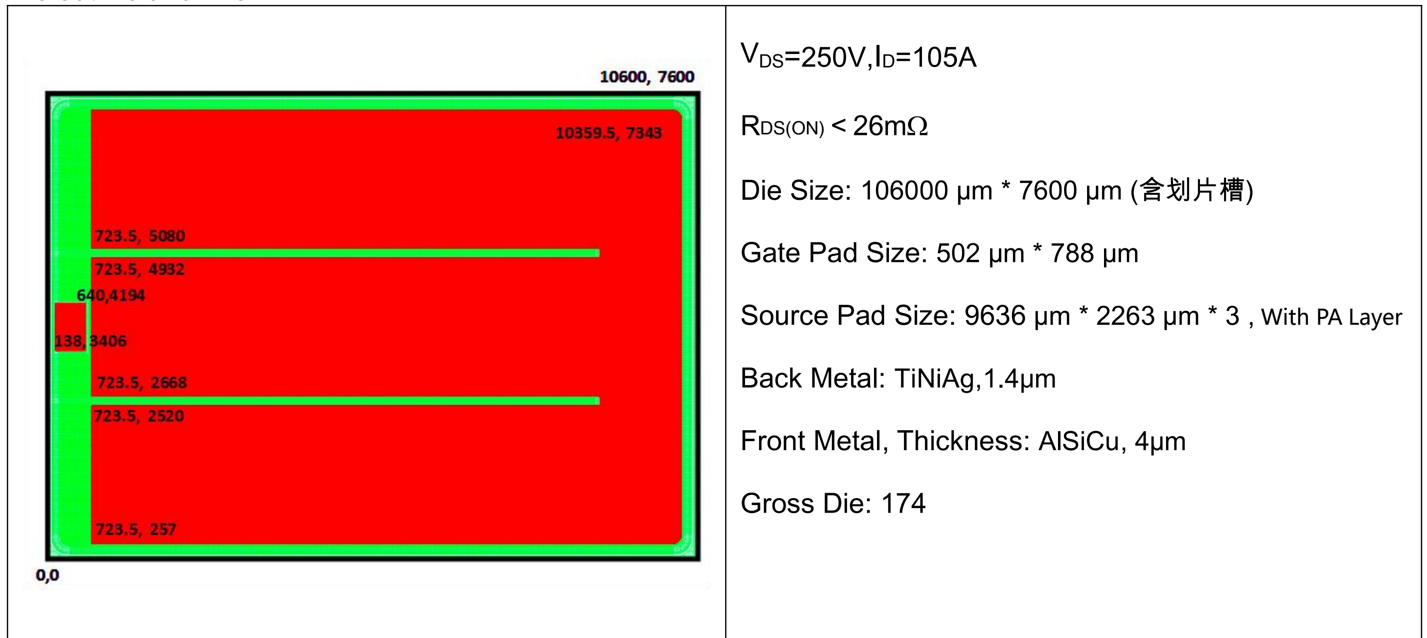
250V MOSFET Wafer

Ordering Information

Wafer Name	CDJX898N250A	Chip Name	/

Die outline and Info.



V_{DS}=250V,I_D=105A

$R_{DS(ON)}$ < 26mΩ

Die Size: 106000 μm * 7600 μm (含划片槽)

Gate Pad Size: 502 μm * 788 μm

Source Pad Size: 9636 μm * 2263 μm * 3 , With PA Layer

Back Metal: TiNiAg,1.4μm

Front Metal, Thickness: AlSiCu, 4μm

Gross Die: 174

Mechanical Data

Nominal Back Metal Composition:	TiNiAg 1.4μm
Nominal Front Metal Composition, Thickness:	AlSiCu(98.5%-1%-0.5%）4μm
Wafer Diameter:	150 mm (6 inch)
Wafer Thickness:	300μm+/-20μm
Minimum Street Width	60μm
Reject Ink Dot	ink
Recommended Storage Environment:	Store in original container, in desiccated nitrogen, with no contamination
Recommended Die Attach Conditions:	For optimum electrical results, die attach temperature should not exceed 300 °C

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Electrical Characteristic Note*

(Device Major Electrical Characteristics for TO-247H package Reference；T_J=25°C unless otherwise specified.)

Parameter	Description	Min.	Typ.	Max.	Test Conditions	Unit
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	250	--	--	V_{GS} = 0V, I_D = 250μA	V
V_{GSS}	Gate-to-Source Voltage	--	--	±30	NA	V
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	--	21	26	V_{GS} = 10V, I_D = 52.5A	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	2.0	--	4.0	V_{DS} = V_{GS}, I_D = 250μA	V
I_{DSS}	Drain-to-Source Leakage Current	--	--	1	V_{DS} = 250V, V_{GS} = 0V, T_J = 25°C	uA
I_{GSS}	Gate-to-Source Leakage Current	--	--	±100	V_{GS} = ±30V	nA
V_{SD}	Body Diode Voltage	--	--	1.5	V_{GS} = 0V, I_{SD} = 105A	V
T_j	Operating Junction and	-55°C to 150 °C Max.				°C
T_{STG}	Storage Temperature Range					

Note*

Electrical characteristics are reported for the reference packaged part (TO-247H) and can not be guaranteed in die sales form. Variations in customer packaging materials, dimensions and processes may affect parametric performance.

Shipping

- One shipping options is offered as standard.
- Un-sawn wafer

Handling

- Product must be handled only at ESD safe workstations. Standard ESD precautions and safe work environments are as defined in MIL-HDBK-263.
- Product must be handled only in a class 10,000 or better-designated clean room environment.

Wafer/Die Storage

- Proper storage conditions are necessary to prevent product contamination and/or degradation after shipment.
- Un-sawn wafers and singulated die can be stored for up to 12 months when in the original sealed packaging at room temperature (45% +/- 15% RH controlled environment).
- Un-sawn wafers and singulated die that have been opened can be stored when returned to their containers and placed in a Nitrogen purged cabinet, at room temperature (45% +/- 15% RH controlled environment).
- Note: To reduce the risk of contamination or degradation, it is recommended that product not being used in the assembly process be returned to their original containers and resealed with a vacuum seal process.
- Sawn wafers on a film frame are intended for immediate use and have a limited shelf life.

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